### **Power MOSFET**

# -20 V, -1.3 A, P-Channel SOT-23 Package

These miniature surface mount MOSFETs low  $R_{DS(on)}$  assure minimal power loss and conserve energy, making these devices ideal for use in space sensitive power management circuitry. Typical applications are DC–DC converters and power management in portable and battery–powered products such as computers, printers, PCMCIA cards, cellular and cordless telephones.

#### **Features**

- Low R<sub>DS(on)</sub> Provides Higher Efficiency and Extends Battery Life
- Miniature SOT-23 Surface Mount Package Saves Board Space
- Pb-Free Packages are Available

### **MAXIMUM RATINGS** (T<sub>J</sub> = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Drain-to-Source Voltage	V <sub>DSS</sub>	-20	V
Gate-to-Source Voltage - Continuous	V <sub>GS</sub>	±12	V
Drain Current - Continuous @ $T_A = 25^{\circ}C$ - Pulsed Drain Current ( $t_p \le 10 \mu s$ )	I <sub>D</sub> I <sub>DM</sub>	-1.3 -4.0	A A
Total Power Dissipation @ T <sub>A</sub> = 25°C	$P_{D}$	400	mW
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	– 55 to 150	°C
Thermal Resistance – Junction–to–Ambient	$R_{\theta JA}$	300	°C/W
Maximum Lead Temperature for Soldering Purposes, (1/8" from case for 10 s)	T <sub>L</sub>	260	°C

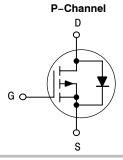
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



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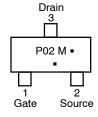
V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub> Max	I <sub>D</sub> Max
-20 V	220 m $\Omega$	-1.3 A



## MARKING DIAGRAM & PIN ASSIGNMENT



SOT-23 CASE 318 STYLE 21



P02 = Specific Device Code

M = Date Code\*
■ Pb-Free Package

(Note: Microdot may be in either location)
\*Date Code orientation may vary depending upon manufacturing location.

### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
NTR1P02LT1	SOT-23	3000 Tape & Reel
NTR1P02LT1G	SOT-23 (Pb-Free)	3000 Tape & Reel
NTR1P02LT3	SOT-23	10,000 Tape & Reel
NTR1P02LT3G	SOT-23 (Pb-Free)	10,000 Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

### $\textbf{ELECTRICAL CHARACTERISTICS} \ (T_A = 25^{\circ}C \ unless \ otherwise \ noted)$

Chara	Symbol	Min	Тур	Max	Unit		
OFF CHARACTERISTICS							
Drain-to-Source Breakdown Voltage ( $V_{GS} = 0 \text{ V}, I_D = -10 \mu\text{A}$ )	V <sub>(BR)DSS</sub>	-20			V		
Zero Gate Voltage Drain Current $(V_{DS} = -16 \text{ V}, V_{GS} = 0 \text{ V})$ $(V_{DS} = -16 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125^{\circ}\text{C})$		I <sub>DSS</sub>			-1.0 -10	μΑ	
Gate-Body Leakage Current (V <sub>GS</sub>	= ± 12 V, V <sub>DS</sub> = 0 V)	I <sub>GSS</sub>			±100	nA	
ON CHARACTERISTICS (Note 1)							
Gate Threshold Voltage (V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = $-250 \mu$ A)	V <sub>GS(th)</sub>	-0.7	-1.0	-1.25	V		
Static Drain-to-Source On-Resista $(V_{GS} = -4.5 \text{ V}, I_D = -0.75 \text{ A})$ $(V_{GS} = -2.5 \text{ V}, I_D = -0.5 \text{ A})$	r <sub>DS(on)</sub>		0.135 0.190	0.22 0.35	Ω		
DYNAMIC CHARACTERISTICS							
Input Capacitance	$(V_{DS} = -5.0 \text{ V})$	C <sub>iss</sub>		225		pF	
Output Capacitance	(V <sub>DS</sub> = -5.0 V)	C <sub>oss</sub>		130			
Transfer Capacitance	(V <sub>DG</sub> = -5.0 V)	C <sub>rss</sub>		55		1	
SWITCHING CHARACTERISTICS	(Note 2)						
Turn-On Delay Time		t <sub>d(on)</sub>		7.0		ns	
Rise Time	$(V_{DD} = -5.0 \text{ V}, I_D = -1.0 \text{ A},$	t <sub>r</sub>		15			
Turn-Off Delay Time	$R_L = 5.0 \Omega$ , $R_G = 6.0 \Omega$ )	t <sub>d(off)</sub>		18			
Fall Time		t <sub>f</sub>		20			
Total Gate Charge	$(V_{DS} = -16 \text{ V}, I_D = -1.5 \text{ A}, V_{GS} = -4.0 \text{ V})$	Q <sub>T</sub>		5500		pC	
SOURCE-DRAIN DIODE CHARAG	CTERISTICS						
Continuous Current		Is			-0.6	А	
Pulsed Current	I <sub>SM</sub>			-0.75			
Forward Voltage (Note 2) (V <sub>GS</sub> = 0	V <sub>SD</sub>			-1.0	V		
Reverse Recovery Time	$(I_S = -1.0 \text{ A}, V_{GS} = 0 \text{ V}, \\ dI_S/dt = 100 \text{ A/}\mu\text{s})$	t <sub>rr</sub>		16		ns	
		t <sub>a</sub>		11		1	
		t <sub>b</sub>		5.5		1	
Reverse Recovery Stored Charge	Q <sub>RR</sub>		0.0085		μC		

Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.
 Switching characteristics are independent of operating junction temperature.

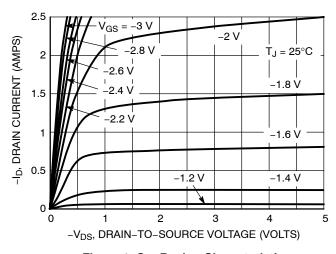


Figure 1. On-Region Characteristics

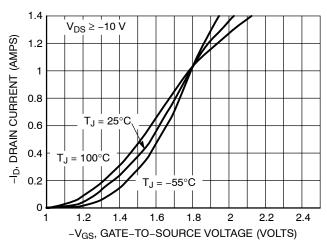


Figure 2. Transfer Characteristics

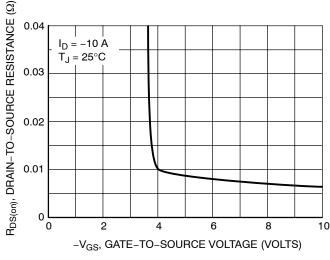


Figure 3. On-Resistance versus Gate-to-Source Voltage

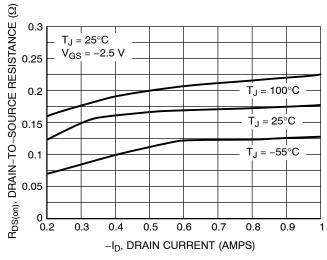


Figure 4. On-Resistance versus Drain Current and Gate Voltage

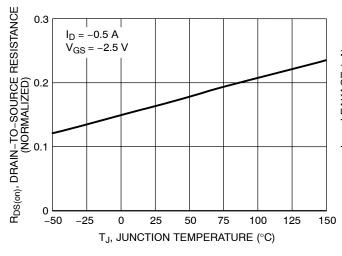


Figure 5. On–Resistance Variation with Temperature

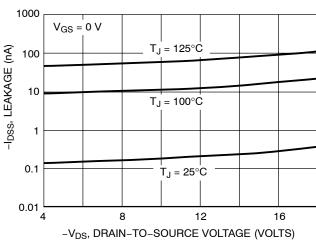


Figure 6. Drain-to-Source Leakage Current versus Voltage

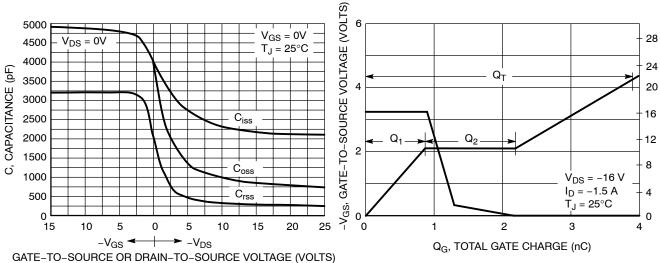


Figure 7. Capacitance Variation

Figure 8. Gate-to-Source and Drain-to-Source Voltage versus Total Charge

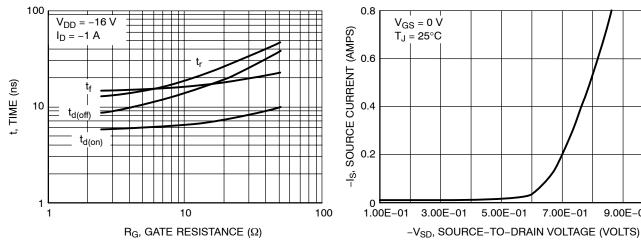


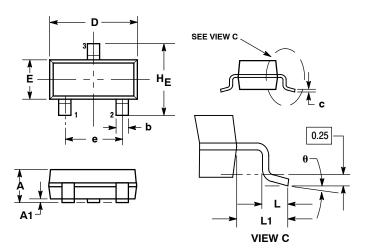
Figure 9. Resistive Switching Time Variation versus Gate Resistance

Figure 10. Diode Forward Voltage versus Current

9.00E-01

#### PACKAGE DIMENSIONS

### SOT-23 (TO-236) CASE 318-08 **ISSUE AN**



#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
  MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF
- 318-01 THRU -07 AND -09 OBSOLETE, NEW STANDARD 318-08.

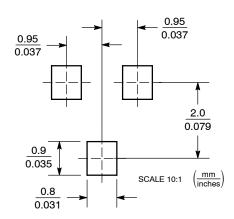
	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
С	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
Е	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.40	2.64	0.083	0.094	0.104

STYLE 21:

PIN 1. GATE SOURCE

DRAIN

### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D

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